

**AMENDMENTS TO THE SPECIFICATION**

Please replace the text from page 6, line 29 to page 7 line 2 with the following amended paragraph:

FIG. 2A depicts the bottom surface of an illustrative embodiment of a Bernoulli end effector 20b that may be used in the system 10. FIG. 2B shows a cross-sectional view of the Bernoulli end effector 20b ~~[[']]~~ of FIG. 2A ~~[[B]]~~. The Bernoulli end effector 20b includes a support member 22, a series of passages 24, an arm 26, at least one edge guide 28, and at least one friction pad 30.

Please replace the text from page 11, lines 26-31 with the following amended paragraph:

Transfer of the substrate 14 is accomplished by substantially simultaneously turning off the first substrate chuck 58 and turning on the second substrate chuck 60. The second substrate chuck 60 receives the substrate 14 from the first substrate chuck 58, thereby exposing the first surface 54 ~~second surface 56~~ of the substrate 14. The end effector 20d is then positioned to receive the substrate 14 from the second substrate chuck 60 after the substrate 14 is flipped.

Please replace the text from page 12, line 29 to page 13 line 8 with the following amended paragraph:

FIG. 6 shows a cross-sectional view of an exemplary substrate handling structure 18' according to the invention. The structure 18' includes a substrate carrier 66, a substrate support feature 68, a substrate clamp 70, at least one guide 72 ~~[[70]]~~, and a secondary base 74. The substrate 14 is placed on the substrate support feature 68 of the substrate carrier 66. The substrate clamp 70 holds the substrate 14 flat during processing of the substrate 14. After processing, the substrate 14, and particularly ultra-thin wafers, are more susceptible to curling, bowing or flexing due to stress applied, e.g., by a film deposited. The substrate clamp 70 also maintains the shape of the substrate 14 until an end effector can remove the substrate from the substrate carrier 66. The

substrate clamp 70 is moveable between a lowered position for securing the substrate 14 and a raised position, which permits the substrate 14 to be placed or retrieved, e.g., by one of the end effectors 20a, 20b, 20c, or 20d.